

STARPOWER

SEMICONDUCTOR™

IGBT

GD75FFK60C6S

Preliminary

Molding Type Module**600V/75A 6 in one-package**

General Description

STARPOWER IGBT Power Module provides ultra low conduction and switching loss as well as short circuit ruggedness. They are designed for the applications such as general inverters and UPS.

Features

- Low $V_{CE(sat)}$ NPT IGBT technology
- 10 μ s short circuit capability
- $V_{CE(sat)}$ with positive temperature coefficient
- Square RBSOA
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology



Typical Applications

- Inverter for motor drive
- AC and DC servo drive amplifier
- Uninterruptible power supply

Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise noted

Symbol	Description	GD75FFK60C6S	Units
V_{CES}	Collector-Emitter Voltage	600	V
V_{GES}	Gate-Emitter Voltage	± 20	V
I_C	Collector Current @ $T_C=25^\circ\text{C}$ @ $T_C=80^\circ\text{C}$	110 75	A
$I_{CM(1)}$	Pulsed Collector Current @ $T_C=80^\circ\text{C}$	150	A
I_F	Diode Continuous Forward Current	75	A
I_{FM}	Diode Maximum Forward Current	150	A
P_D	Maximum power Dissipation @ $T_j=150^\circ\text{C}$	284	W
T_j	Maximum Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-40 to +125	$^\circ\text{C}$
V_{ISO}	Isolation Voltage RMS, $f=50\text{Hz}$, $t=1\text{min}$	2500	V
Mounting Torque	Mounting Screw:M5	3.0 to 6.0	N.m

Notes:

(1) Repetitive rating: Pulse width limited by max. junction temperature

Electrical Characteristics of IGBT $T_C=25^\circ\text{C}$ unless otherwise noted**Off Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{(BR)CES}$	Collector-Emitter Breakdown Voltage	$T_j=25^\circ\text{C}$	600			V
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}$, $V_{GE}=0\text{V}$, $T_j=25^\circ\text{C}$			5.0	mA
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}$, $V_{CE}=0\text{V}$, $T_j=25^\circ\text{C}$			400	nA

On Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=250\mu\text{A}$, $V_{CE}=V_{GE}$, $T_j=25^\circ\text{C}$	3.5	4.5	5.5	V
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=75\text{A}$, $V_{GE}=15\text{V}$, $T_j=25^\circ\text{C}$		1.95	2.40	V
		$I_C=75\text{A}$, $V_{GE}=15\text{V}$, $T_j=125^\circ\text{C}$		2.25		

Switching Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=300V, I_C=75A,$ $R_G=18\Omega, V_{GE}=\pm 15V,$ $T_j=25^\circ C$		217		ns
t_r	Rise Time			72		ns
$t_{d(off)}$	Turn-Off Delay Time			230		ns
t_f	Fall Time			88		ns
E_{on}	Turn-On Switching Loss			1.69		mJ
E_{off}	Turn-Off Switching Loss			1.33		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=300V, I_C=75A,$ $R_G=18\Omega, V_{GE}=\pm 15V,$ $T_j=125^\circ C$		213		ns
t_r	Rise Time			72		ns
$t_{d(off)}$	Turn-Off Delay Time			236		ns
t_f	Fall Time			103		ns
E_{on}	Turn-On Switching Loss			1.79		mJ
E_{off}	Turn-Off Switching Loss			1.80		mJ
C_{ies}	Input Capacitance	$V_{CE}=30V, f=1MHz,$ $V_{GE}=0V$		4.30		nF
C_{oes}	Output Capacitance			0.35		nF
C_{res}	Reverse Transfer Capacitance			0.16		nF
I_{SC}	SC Data	$t_{sc} \leq 5\mu s, V_{GE}=15V,$ $T_j=150^\circ C, V_{CC}=360V,$ $V_{CEM} \leq 600V$		TBD		A
L_{CE}	Stray Inductance			21		nH
$R_{CC'+EE'}$	Module Lead Resistance, Terminal To Chip			1.80		m Ω

Electrical Characteristics of DIODE $T_C=25^\circ C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_F	Diode Forward Voltage	$I_F=75A$	$T_j=25^\circ C$	1.45	1.85	V
			$T_j=125^\circ C$	1.50		
Q_r	Recovered charge	$I_F=75A,$	$T_j=25^\circ C$	3.2		μC
			$T_j=125^\circ C$	4.2		
I_{RM}	Peak Reverse Recovery Current	$V_R=300V,$ $di/dt=-1200A/\mu s,$	$T_j=25^\circ C$	49		A
			$T_j=125^\circ C$	51		
E_{rec}	Reverse Recovery Energy	$V_{GE}=-15V$	$T_j=25^\circ C$	0.76		mJ
			$T_j=125^\circ C$	0.96		

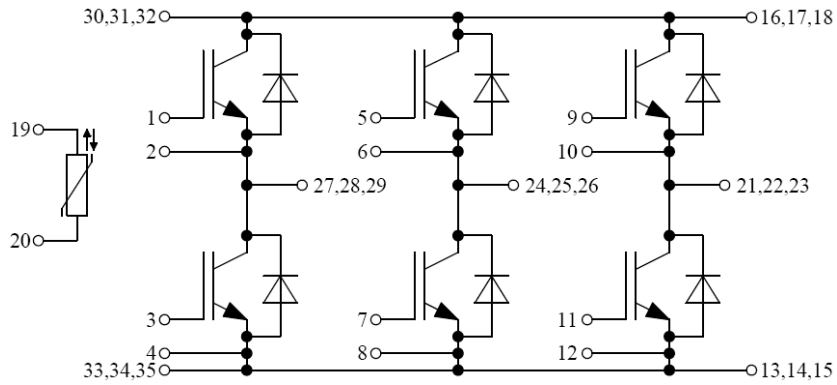
Electrical Characteristics of NTC $T_C=25^{\circ}\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
R_{25}	Rated Resistance			5.0		k Ω
$\Delta R/R$	Deviation of R_{100}	$R_{100}=493.3\Omega$	-5		5	%
P_{25}	Power Dissipation				20.0	mW
$B_{25/50}$	B-value	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15\text{K}))]$		3375		K

Thermal Characteristics

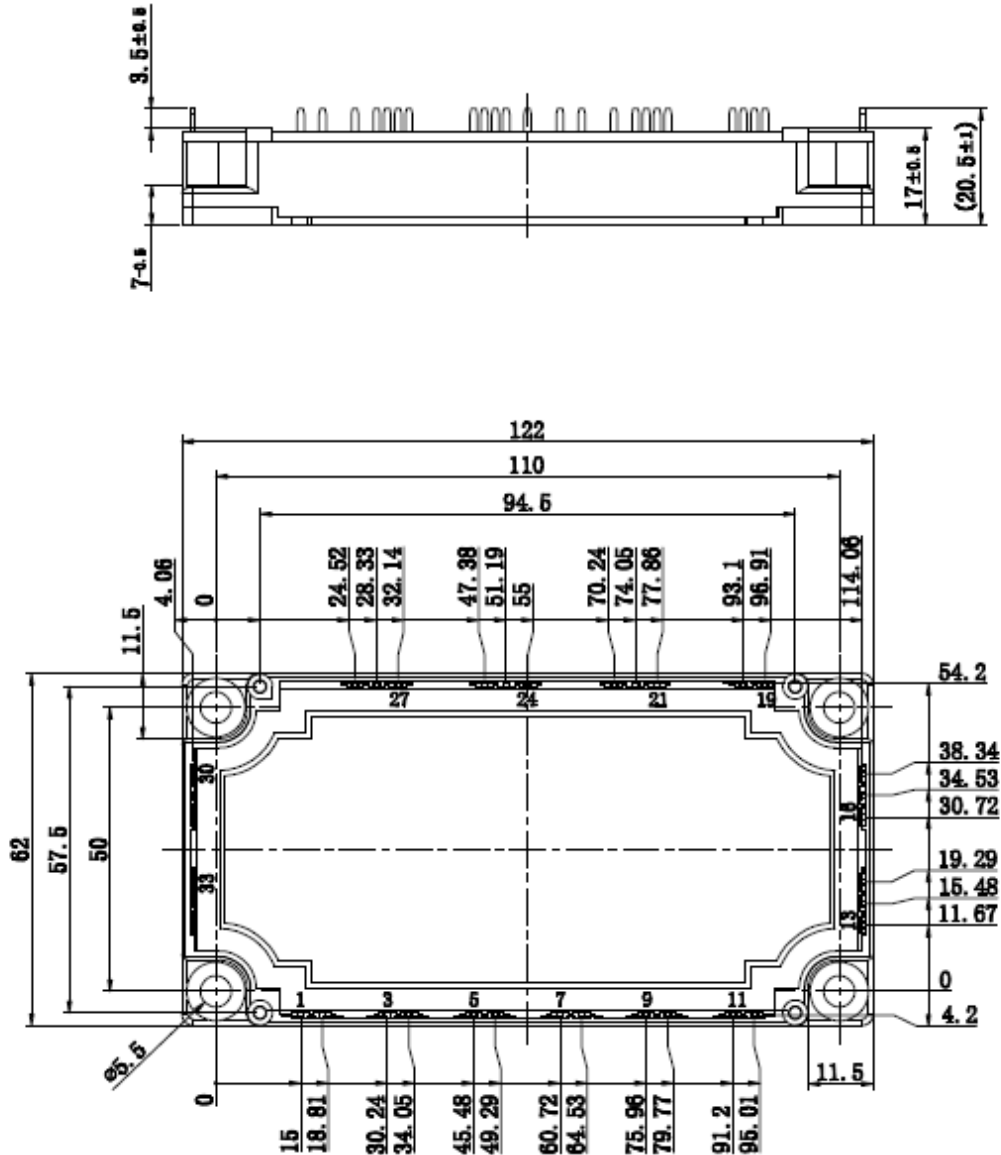
Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case (per IGBT)		0.44	K/W
$R_{\theta JC}$	Junction-to-Case (per DIODE)		0.61	K/W
$R_{\theta CS}$	Case-to-Sink (Conductive grease applied)	0.009		K/W
Weight	Weight of Module	300		g

Equivalent Circuit Schematic



Package Dimension

Dimensions in Millimeters



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